

WHAT IS CLAIMED IS:

1. A gettering property evaluating method for evaluating gettering property of a semiconductor wafer having a plurality of devices formed on a front surface thereof, the gettering property evaluating method comprising:

a gettering layer forming step of polishing a back surface opposite to the front surface of the semiconductor wafer by use of a polishing wheel to form polishing marks on the back surface and to form a gettering layer inside the semiconductor wafer and beneath the polishing marks;

an imaging step of imaging at least a unit region of the back surface formed with the polishing marks by imaging means;

a counting step of counting the number of the polishing marks having a width of 10 to 500 nm present in the unit region imaged; and

a comparing step of comparing the number of the polishing marks counted by the counting step with a predetermined value to determine whether or not the counted number is not less than the predetermined value,

wherein in the comparing step a state of the gettering layer is evaluated based on the counted number of the polishing marks.

2. The gettering property evaluating method according to claim 1, wherein the area of the unit region is 10 pmt, and the predetermined value is eight per 10 μm^2 .

3. A gettering property evaluating method for evaluating gettering property of a semiconductor wafer having a plurality of devices formed on a front surface

thereof, the gettering property evaluating method comprising:

a gettering layer forming step of polishing a back surface opposite to the front surface of the semiconductor wafer by use of a polishing wheel to form polishing marks on the back surface and to form a gettering layer inside the semiconductor wafer and beneath the polishing marks;

an imaging step of imaging at least a unit region of the back surface formed with the polishing marks by imaging means;

a counting step of counting the number of the polishing marks having a width of 10 to 500 nm present in the unit region imaged; and

a comparing step of comparing the number of the polishing marks counted by the counting step with a predetermined value to determine whether or not the counted number is not less than the predetermined value,

wherein in the comparing step a state of the gettering layer is evaluated based on the counted number of the polishing marks,

wherein the number of the polishing marks is counted by detecting a selected pixel having color information different from that of a flat formed part of the back surface, and when the selected pixel is detected, a number of other pixels appearing in series in the case where a series of other pixels have the same color information as that of the selected pixel is counted, and

when the number of the other pixels appearing in series is not less than a predetermined number, the selected pixel and the other pixels are decided to constitute a polishing mark.